

PATENT ABSTRACTS OF JAPAN

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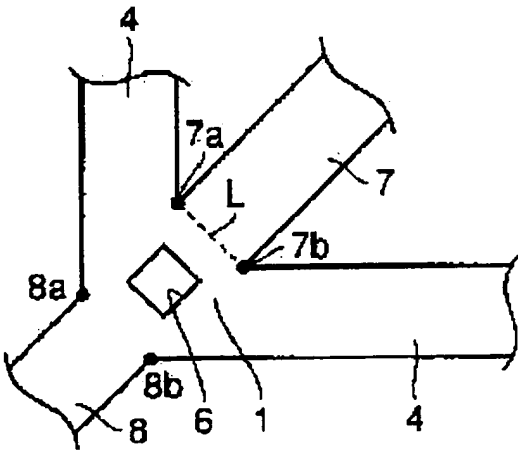
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(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device having a resin peeling prevention hole and provided with a lead frame difficult to concentrate deformation in the neighborhood thereof.

SOLUTION: The resin peeling prevention hole 5 is provided on the intersection part 1 of a reinforcing frame 4 and an inside hanging lead 7 in the lead frame, and positioned on the intersection part of the area of the contrary side of a die pad rather than a line L connecting first and second inside hanging lead root boundary points 7a, 7b being a point in which the reinforcing frame continues to both the side parts of an inside hanging lead extending from the intersection part.



LEGAL STATUS

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